BRIGHTEK (EUROPE) LIMITED ! Brighten up The World With CED !



PRODUCT DATASHEET



- ► Chip Side View with IC
- 1204SV (3210) IC 1.5t
 Sky White/Red/Green /Blue

NOM65S99ICSV



1204SV IC-LED



FEATURES (White/Red/Green/Blue*):

- Package: CHIP Side View Package with Integrated IC
- Forward Current: 12/12/12/12mA*
- Forward Voltage (typ.): +3.0~+5.5V
- Luminous Intensity (typ.): 430/280/490/100mcd
- Colour: Sky White/Red/Green/Blue
- CCT/Dominant Wavelength (typ.): 12000K/622/522/467nm
- Viewing Angle: 120°
- Materials:
 - Die: InGaN/AlGaInP/InGaN/InGaN
 - Resin: Epoxy (White Diffused)
- **Operating Temperature:** -40~+85°C
- Storage Temperature: -40~+100°C
- IC Features: This IC LED product is much smaller than PLCC type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Soldering Methods: IR Reflow soldering
- MSL Level: acc. to JEDEC Level 3
- Packing: 8mm tape with max.3000pcs/reel, ø180mm (7")
 - * in order of White/White/Red/Green/Blue

1204SC IC-Integrated

APPLICATIONS:

- Telecommunication
- Indicator
- Home Appliance
- Decoration Lighting
- Full Colour LED Strip
- Gaming Device
- Guardrail Tube



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
LED Output Current	Іоит	25	mA
Supply Voltage	V _{DD}	6.5	V
Power Dissipation	PD	400	mW
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	Tstg	-40~+100	°C

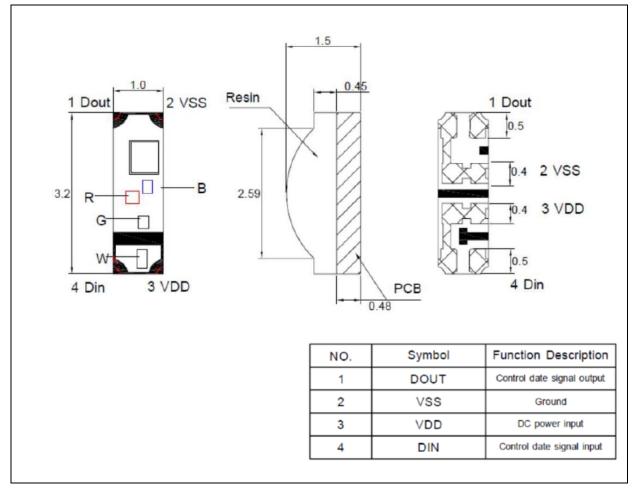
Electrical & Optical Characteristics (Ta=25°C, V_{DD}=5V)

Parameter		Course la sel	-	Values	11	Test	
		Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage		VF	3.0	5.0	5.5	V	
Each R/G/B Current		I _{OL}		12		mA	V _{DD} =5V
Input High Voltage		VIH	2.7		V _{DD}	V	DI
Input Low Voltage		VIL	0		1.0	V	DI
Output High Voltage	Output High Voltage		4.5			V	I _{OH} =4mA
Output Low Voltage		Vol			$0.4 V_{DD}$	V	I₀∟=4mA
Pull Down Resistance		R _{PD}		500K		Ω	D _{IN} , D _{OUT} (VDD=5V)
Luminous Intensity	R	- Iv	125	280	500	mcd	V _{DD} =5V
	G		200	490	800		
	В		50	100	200		
	W		200	430	800		
	R	λ _D	615		630	nm	V _{DD} =5V
Dominant Wavelength	G		515		530		
	В		460		475		
Viewing Angle		20 _{1/2}		120		deg	I⊧=12mA



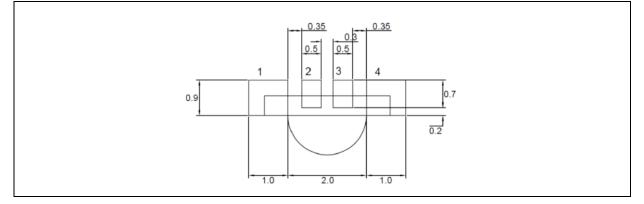
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

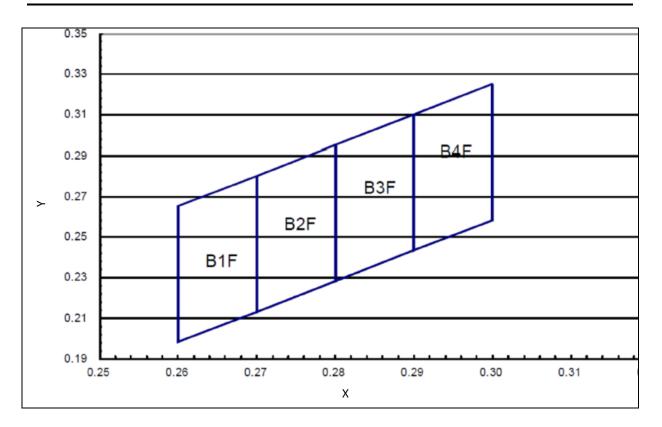
Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^{\circ}$.



CIE CHROMATICITY DIAGRAM:

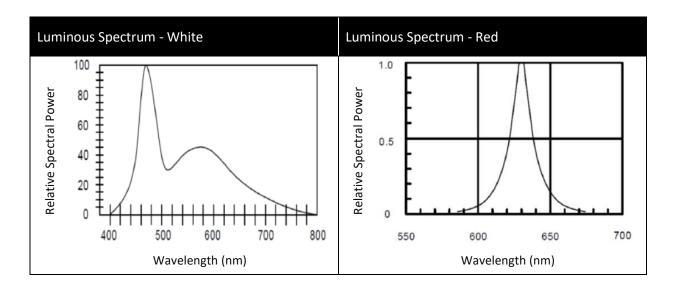


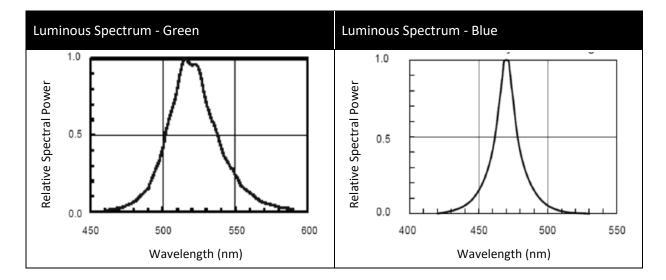
Chromaticity Coordinates Classifications:

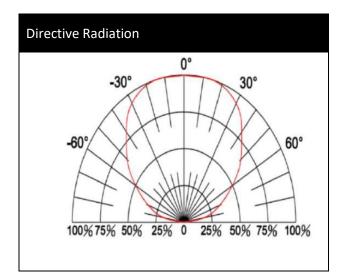
	1	L	2		3		4	
	Х	Y	Х	Y	Х	Y	Х	Y
B1F	0.2600	0.2650	0.2600	0.1980	0.2700	0.2130	0.2700	0.2800
B2F	0.2700	0.2800	0.2700	0.2130	0.2800	0.2280	0.2800	0.2950
B3F	0.2800	0.2950	0.2800	0.2380	0.2900	0.2430	0.2900	0.3100
B4F	0.2900	0.3100	0.2900	0.2430	0.3000	0.2580	0.3000	0.3250



ELECTRO-OPTICAL CHARACTERISTICS:



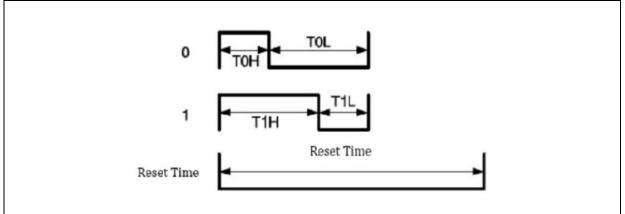






Function Description:

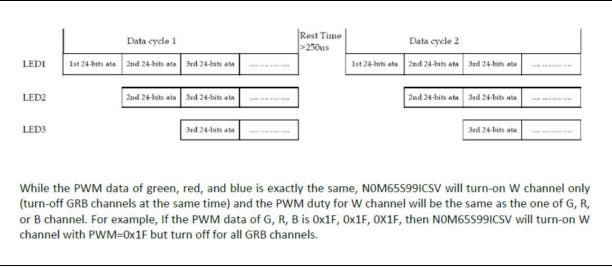
1. Timing Wave Form:



2. High Speed Mode:

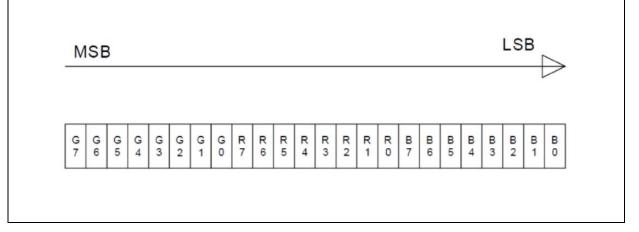
Item	Description	min	Typical	Allowance	unit
тон	0 code, High-level time		0.3	±0.15	us
TOL	0 code, Low-level time		0.9	±0.15	us
T1H	1 code, High-level time		0.9	±0.15	us
T1L	1 code, Low-level time		0.3	±0.15	us
Trst	Reset code,Low-level time	250			

3. Data Communication:





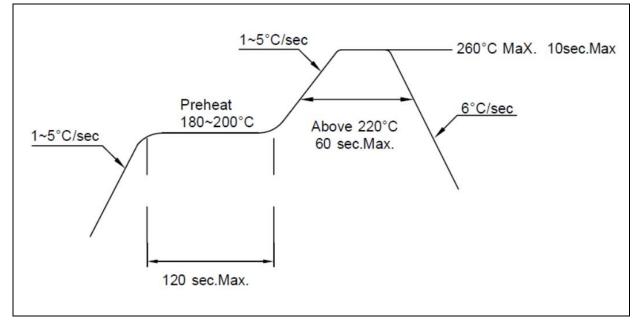






RECOMMENDED SOLDERING PROFILE:





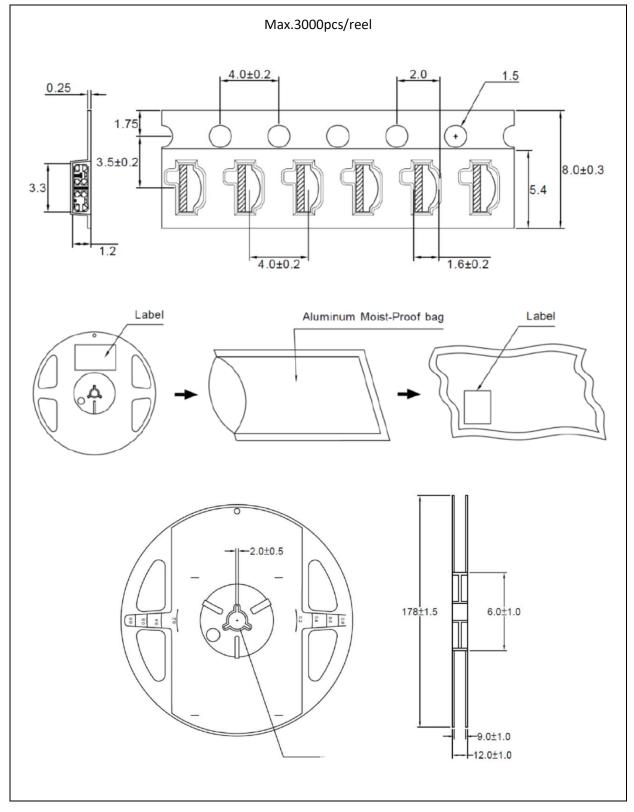
Note:

- 1. We recommend the reflow temperature 240°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Maxima reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 168 hours. Otherwise, they should be kept in a damp-proof box with descanting agent stored at R.H.<10% and apply baking before use.

Over-Current Proof:

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burnout will happen.

Baking:

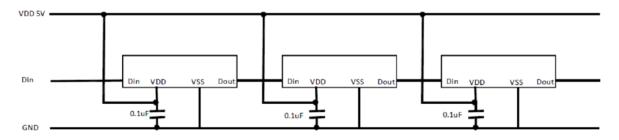
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Recommended Route:

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Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	25/10/2023	Datasheet set-up.